

IN THE CLAIMS:

Claim 9 was previously cancelled. Claim 8 has been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

**Listing of Claims:**

1. (Previously presented) An encapsulation method for a plurality of electronic devices within a mold cavity, the mold cavity formed by an upper and lower mating mold plates having a mold cavity portion, each mold cavity portion of the upper and lower mating mold plates having a feed runner leading thereto from a material supply and having a vent runner connected thereto for venting each mold cavity portion, the mold cavity portions together comprising the mold cavity for an electronic device, comprising:  
placing a first substrate having a first side, a second side, and at least one electronic component on the first side of the first substrate and a second substrate having a first side, second side, and at least one electronic component on the first side of the second substrate into the mold cavity;  
moving the upper and lower mating mold plates toward each other to form the mold cavity, portions of the upper mating mold plate engaging portions of the first surface of the first substrate and portions of the lower mating mold plate engaging portions of the first surface of the second substrate, the moving of the upper and lower mating mold plates toward each other causing the second side of the first substrate and the second side of the second substrate to have portions thereof in contact;  
injecting a first material into the mold cavity portion of the upper mating mold plate and a second material into the mold cavity portion of the lower mating mold plate to separately encapsulate the at least one electronic component on the first side of the first substrate and the at least one electronic component on the first side of the second substrate, the second material comprising one of the first material and a similar material; and

removing the first substrate and the second substrate from the upper and lower mating mold plates.

2. (Previously presented) The method of claim 1, wherein the injecting the second material into the mold cavity portion of the lower mating mold plate comprises injecting a material substantially identical to the first material.

3. (Previously presented) The method of claim 1, wherein the injecting the second material into the mold cavity portion of the lower mating mold plate comprises injection of a material substantially different from the first material.

4. (Previously presented) The method of claim 1, wherein the first material and the second material are injected substantially simultaneously.

5. (Previously presented) The method of claim 1, wherein the first material and the second material are injected at different times.

6. (Previously presented) The method of claim 1, further comprising cleaning the second side of each of the first substrate and the second substrate.

7. (Previously presented) The method of claim 1, further comprising curing the plurality of electronic devices at an elevated curing temperature.

8. (Currently amended) An encapsulation method for a plurality of electronic devices within a mold cavity of an encapsulation apparatus, the encapsulation apparatus having upper and lower mating mold plates, each of the upper and lower mating mold plates having a mold cavity portion, each mold cavity portion of the upper and lower mating mold plates having a feed runner leading thereto from a material supply and having a vent runner connected thereto for venting each mold cavity portion, each mold cavity portions together comprising the mold cavity of the encapsulation apparatus, the method comprising:

providing a first substrate having a first side, a second side, and at least one electronic component located on the first side of the first substrate;

providing a second substrate having a first side, a second side, and at least one electronic component located on the first side of the second substrate;

placing a first substrate having a first side, a second side, and at least one electronic component located on the first side of the first substrate and a second substrate having a first side, a second side, and at least one electronic component located on the first side of the second substrate, the second side of the first substrate and the second side of the second substrate placed in a back-to-back-orientation; orientation;

moving the upper and lower mating mold plates to form the mold cavity, portions of the upper mating mold plate engaging portions of the first side of the first substrate and portions of the lower mating mold plate engaging portions of the first side of the second substrate and causing the second side of the first substrate and the second side of the second substrate to have portions thereof in engagement;

injecting a first material into the mold cavity portion of the upper mating mold plate and a second material into the mold cavity portion of the lower mating mold plate to separately encapsulate the first side of each of the first and second substrates, the second material comprising one of the first material and a similar material; and

removing the plurality of electronic devices from the mold cavity.

9. (Canceled)

10. (Previously presented) The method of claim 8, wherein the injecting the second material into the mold cavity portion of the lower mating mold plate comprises injecting a material substantially identical to the first material.

11. (Previously presented) The method of claim 8, wherein injecting the second material into the mold cavity portion of the lower mating mold plate comprises injecting a material substantially different from the first material.

12. (Previously presented) The method of claim 8, wherein the first material and the second material are injected substantially simultaneously.

13. (Previously presented) The method of claim 8, wherein the first material and the second material are injected at different times.

14. (Previously presented) The method of claim 8, further comprising cleaning the second side of each of the first substrate and the second substrate.

15. (Previously presented) The method of claim 8, further comprising subjecting the plurality of electronic devices to a curing temperature.

16. (Previously presented) The method of claim 8, wherein the second side of each of the first substrate and the second substrate includes solder bumps thereon.